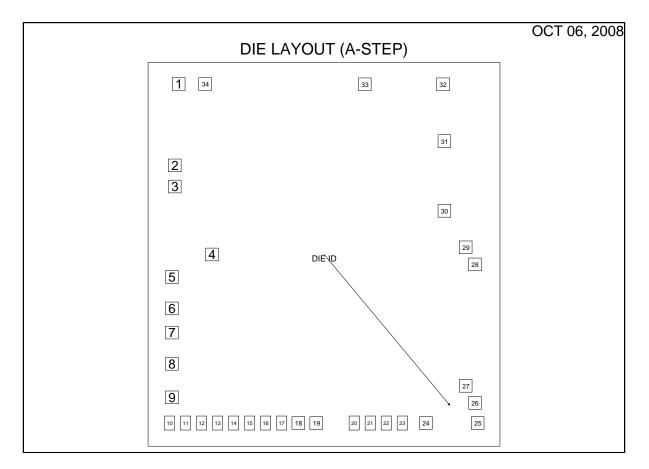


LM5575Q0 MDC MCD2870A

SIMPLE SWITCHER® 75V, 1.5A STEP-DOWN SWITCHING REGULATOR



DIE/WAFER CHARACTERISTICS

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Fabrication Attributes		General Die Information	
Physical Die	LM5575A	Bond Pad Opening	91.00µm x 91.00µm
Identification		Size (min)	
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	2514.60µm x 2743.20µm	Back Side Connection	Floating
	99.0mils x 108.0mils		
Thickness	254µm Nominal		
Min Pitch	128µm		
Note: All values are round	ded to the nearest micron.		
Special Assembly Requir	ements:		



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Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Х	Y	Х		Y
SD	1	-1039	1217	91	Х	91
VIN	2	-1067	636	91	х	91
VIN	3	-1067	485	91	х	91
VIN	4	-801	-1	91	х	91
SYNC	5	-1087	-162	91	х	91
COMP	6	-1087	-387	91	х	91
FB	7	-1087	-559	91	х	91
RT	8	-1087	-783	91	х	91
RAMP	9	-1087	-1022	91	х	91
NC	10	-1104	-1206	73	х	100
NC	11	-990	-1206	73	х	100
NC	12	-875	-1206	73	х	100
NC	13	-761	-1206	73	х	100
NC	14	-646	-1206	73	х	100
NC	15	-532	-1206	73	х	100
NC	16	-417	-1206	73	х	100
NC	17	-303	-1206	73	х	100
AGND	18	-184	-1206	91	х	91
AGND	19	-56	-1206	91	х	91
NC	20	216	-1206	73	х	100
NC	21	331	-1206	73	х	100
NC	22	445	-1206	73	х	100
NC	23	560	-1206	73	х	100
SS	24	728	-1206	91	х	91
OUT	25	1098	-1206	91	х	91
PGND	26	1079	-1062	91	х	91
PGND	27	1013	-940	91	х	91
IS	28	1079	-72	91	х	91
IS	29	1013	50	91	х	91
SW	30	861	311	91	х	91
SW	31	861	809	91	х	91
PRE	32	851	1215	91	х	91
BST	33	292	1215	91	х	91
VCC	34	-850	1217	91	х	91



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